

In the Specification:

Please amend the section "Cross Reference to Related Applications" as follows:

CROSS-REFERENCE TO RELATED APPLICATIONS

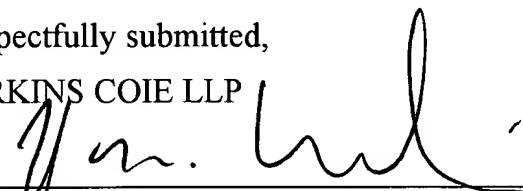
21 The present application is a continuation-in-part of U.S. Application No. 09/651,779, titled "Methods and Apparatus for Removing Conductive Material From a Microelectronic Substrate," filed August 30, 2000. Additionally, this application is related to U.S. Application No. 09/887,767 (attorney docket number 108298515US2), titled "Microelectronic Substrate Having Conductive Material with Blunt Cornered Apertures, and Associated Methods for Removing Conductive Material," filed June 21, 2001, and U.S. Application No. 09/888,002 (attorney docket number 108298515US3), titled "Methods and Apparatus for Electrically and/or Chemically-Mechanically Removing Conductive Material from a Microelectronic Substrate," filed June 21, 2001. All of the U.S. Patent Applications listed above are incorporated herein by reference.

REMARKS

Applicants respectfully request consideration of the application in view of this preliminary amendment. If the Examiner has any questions or matters that can be expediently handled by telephone, he or she is encouraged to contact Mr. Wechkin, attorney for the Applicants.

Respectfully submitted,

PERKINS COIE LLP


John M. Wechkin

Registration No. 42,216

JMW:ri

PERKINS COIE LLP
1201 Third Avenue, Suite 4800
Seattle, Washington 98101-3009
(206) 583-8888
FAX: (206) 583-8500

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